IPC/JPCA-4591

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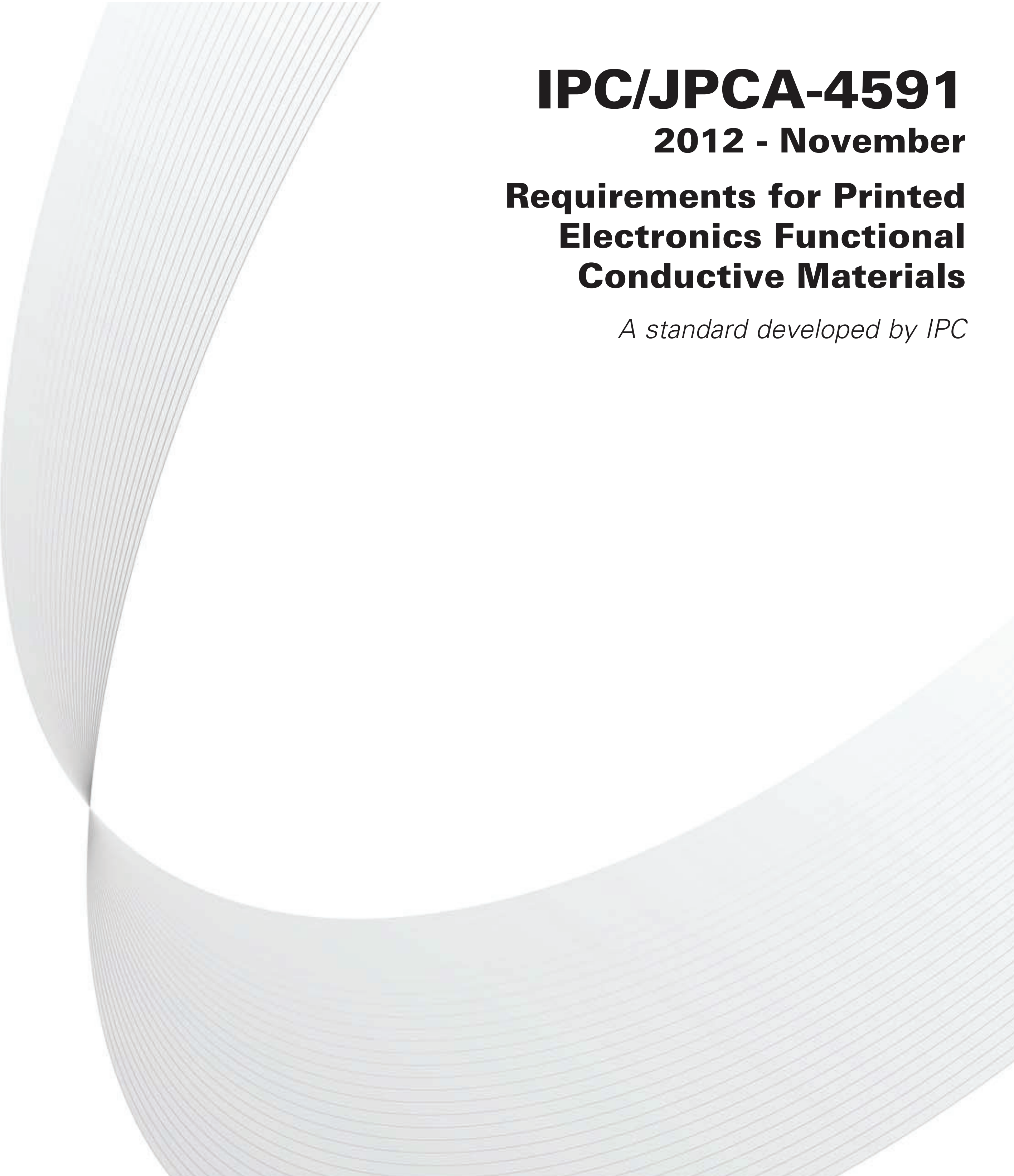
Requirements for Printed Electronics Functional Conductive Materials

A standard developed by IPC



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- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

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- Inhibit innovation
- Increase time-to-market
- Keep people out
- Increase cycle time
- Tell you how to make something
- Contain anything that cannot be defended with data

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Requirements for Printed Electronics Functional Conductive Materials

Developed by the Printed Electronics Functional Materials Subcommittee (D-63) of the Printed Electronics Committee (D-60) of IPC

Users of this publication are encouraged to participate in the development of future revisions.

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